

Water-based cleaning medium for flux removal



VIGON® US is a water-based medium specifically developed for the use in ultrasonic, spray-under-immersion and centrifugal cleaning equipment. Based on MPC[®] Technology, VIGON[®] US removes all types of flux residues from electronic assemblies, ceramic hybrids and lead frames.

Areas of application: PCB's, ceramic hybrids, power modules, lead frames		Additional product information:	
Low solid flux residues*	++	Technical Information 2:	
Rosin-based flux residues*	++	Overview of all fluxes and solder pastes tested	
Water soluble flux residues*	++	Technical Information 3: Overview regarding material compatibility Application Recommendation: Specific process parameters for your cleaning trial MPC® Technology Information Sheet: Additional information on MPC® Technology	
Solder pastes (unsoldered)	++		
SMT-adhesives or conductive adhesives	-		
Misprinted thick film pastes	+		
++ highly recommended, best results + recommended 0 possible - not recommended			

* Valid for all standard, lead-free and lead-based solders

Technical Centers - 1) America, 2) Europe, 3) Malaysia, 4) North-China, 5) South-China **Cleaning Process Solutions under Production Floor Conditions**



Contact ZESTRON's Process Engineering Team for free-of-charge cleaning trials: Phone: +49-841-635-26; Email: techsupport@zestron.com

Advantages compared to other cleaners:

- Due to its wide process window VIGON® US easily removes flux residues and solder pastes.
- VIGON® US has no flash point and does not require explosion proof equipment.
- The cleaning medium was specifically designed for the use in dip tank systems.
- Due to its formulation, VIGON® US can be easily rinsed without leaving residues on the surface and provides low ionic contamination of cleaned parts.
- Its high bath loading capacity ensures an extended bath life, low maintenance and reduced cleaning agent costs.
- VIGON[®] US works exceptionally well for the cleaning in capillary spaces and is also suitable for cleaning under low standoff components.
- Low odor.

Please refer to the material compatibility list (Technical Information 3) before cleaning plastics.

VIGON® US is approved by leading international cleaning equipment manufacturers. Written approvals can be obtained from ZESTRON.

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Process Steps	1. Cleaning	2. Rinsing	3. Drying
Ultrasonic	VIGON [®] US	DI-water	Hot or circulated air
Spray-under-immersion	VIGON [®] US	DI-water	Hot or circulated air
Centrifugal cleaning	VIGON [®] US	DI-water	Hot air

Technical Data

Please note that the information below represents VIGON [®] US at 20 % concentration.			
Density	(g/ccm) at 20°C/68°F	0.99	
Surface tension	(mN/m) at 25°C/77°F	30.8	
Boiling range	°C/°F	165 – 212 / 329 – 414	
Flash point	°C/°F	None	
pH-value	10g/l H ₂ O	11	
Vapor pressure	(mbar) bei 20°C/68°F	19	
Cleaning temperature	°C/°F	40 – 60 / 104 – 140	
Solubility in water		Soluble	
Application concentration ¹	Concentrate in %	15 – 30	
HMIS Rating	Health-Flammability-Reactivity	0 - 0 - 0	

¹ VIGON[®] US is recommended to be diluted with DI-water only.

PRODUCT FEATURES



Extensively tested and suitable for cleaning of lead-free solder pastes

100% compliance with EU

guidelines (RoHS 1 & 2, WEEE)



MPC[®] Technology ensures an extremely long bath life when used in a closed loop system Product is free of any critical substances according to SIN &

release date: 08.06.11

SVHC lists

Filter recommendation:

- To take full advantage of the MPC[®] technology and further extend the bath life of VIGON[®] US, filtration is recommended.
- For details, please request our "Filter Recommendation" sheet.

Environmental and health and safety regulations:

- VIGON[®] US is formulated free of any halogenated compounds and is environmentally friendly.
- Refer to the MSDS for specific handling precautions and instructions.

Availability/Storage:

- VIGON[®] US is available as concentrate solution in 11 bottles, 51 or 251 containers and 2001 drums.
- Store VIGON[®] US in the original container at a temperature between 5 - 30°C / 41 - 86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

Alternative product recommendation:

 For application in spray-in-air systems such as inline and batch equipment, we recommend the MPC[®] based cleaner VIGON[®]A 201.

Cleaning standards:

Electronic assemblies cleaned with VIGON[®] US in a ZESTRON specified process meet the following industry standards:

- IPC-A-610 Visual cleanliness
- J-STD 001 Ionic and resin cleanliness
- IPC-TM 650 and DIN 32513 (surface resistance)
- J-STD 003 Solderability

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